

1.0 Features

- Phase-locked loop (PLL) device synthesizes output clock frequency from crystal oscillator or external reference clock
- On-chip tunable voltage-controlled crystal oscillator • (VCXO) allows precise system frequency tuning
- Typically used for generation of MPEG-2 decoder . clock
- 3.3V supply voltage •
- Small circuit board footprint (8-pin 0.150" SOIC)
- Custom frequency selections available contact your local AMI Sales Representative for more information

XOUT XIN 8 VSS VDD XTUNE 6 n/c VSS CLK 8-pin (0.150") SOIC Figure 2: Block Diagram XIN VCXO PLL DIVIDER XOUT **XTUNE** FS6128

Figure 1: Pin Configuration

ISC9001

2.0 Description

The FS6128 is a monolithic CMOS clock generator IC designed to minimize cost and component count in digital video/audio systems.

At the core of the FS6128 is circuitry that implements a voltage-controlled crystal oscillator when an external resonator (nominally 13,5MHz) is attached. The VCXO allows device frequencies to be precisely adjusted for use in systems that have frequency matching requirements, such as digital satellite receivers.

A high-resolution phase-locked loop generates an output clock (CLK) through a post-divider. The CLK frequency is ratiometrically derived from the VCXO frequency. The locking of the CLK frequency to other system reference frequencies can eliminate unpredictable artifacts in video systems and reduce electromagnetic interference (EMI) due to frequency harmonic stacking.

Table 1: Crystal / Output Frequencies

DEVICE f _{XIN} (MHz)	CLK (MHz)	XTUNE Range
FS6128-01 13.5	27	0-2 V

CLK



Table 2: Pin Descriptions

Key: AI = Analog Input; AO = Analog Output; DI = Digital Input; DI^U = Input with Internal Pull-Up; DI_D = Input with Internal Pull-Down; DIO = Digital Input/Output; DI-3 = Three-Level Digital Input, DO = Digital Output; P = Power/Ground; # = Active Low pin

PIN	TYPE	NAME	DESCRIPTION
1	AI	XIN	VCXO Feedback
2	Р	VDD	Power Supply (+3.3V)
3	AI	XTUNE	VCXO Tune
4	Р	VSS	Ground
5	DO	CLK	Clock Output
6	-	n/c	No Connection
7	DO	VSS	Ground
8	AO	XOUT	VCXO Drive

3.0 Functional Block Description

3.1 Phase-Locked Loop (PLL)

The on-chip PLL is a standard frequency- and phaselocked loop architecture. The PLL multiplies the reference oscillator to the desired frequency by a ratio of integers. The frequency multiplication is exact with a zero synthesis error.

3.2 Voltage-Controlled Crystal Oscillator (VCXO)

The VCXO provides a tunable, low-jitter frequency reference for the rest of the FS6128 system components. Loading capacitance for the crystal is internal to the FS6128. No external components (other than the resonator itself) are required for operation of the VCXO.

Continuous fine-tuning of the VCXO frequency is accomplished by varying the voltage on the XTUNE pin. The value of this voltage controls the effective capacitance presented by the VCXO to the crystal.

When using a crystal with a VCXO, it is important that the crystal load capacitance (as specified in Table 4: Operating Conditions be matched to the load capacitance as presented by the VCXO. The crystal must be specified with the correct load capacitance to obtain the maximum tuning range. The oscillator operates the crystal resonator in the parallel-resonant mode. Crystal warping, or the "pulling" of the crystal oscillation frequency, is accomplished by altering the effective load capacitance presented to the crystal by the oscillator circuit. The actual amount that changing the load capacitance alters the oscillator frequency will be dependent on the characteristics of the crystal as well as the oscillator circuit itself.

Specifically, the motional capacitance of the crystal (usually referred to by crystal manufacturers as C_1), the static capacitance of the crystal (C_0), and the load capacitance (C_L) of the oscillator determine the warping capability of the crystal in the oscillator circuit.

A simple formula to obtain the warping capability of a crystal oscillator is:

$$\Delta f(ppm) = \frac{C_1 \times (C_{L2} - C_{L1}) \times 10^6}{2 \times (C_0 + C_{L2}) \times (C_0 + C_{L1})}$$

where C_{L1} and C_{L2} are the two extremes of the applied load capacitance.

EXAMPLE: A crystal with the following parameters is used. With $C_1 = 0.02pF$, $C_0 = 5pF$, $C_{L1} = 13pF$, and $C_{L2} = 35pF$, the coarse tuning range is

$$\Delta f = \frac{0.02 \times (35 - 13) \times 10^6}{2 \times (5 + 35) \times (5 + 13)} \approx 305 \, ppm \,.$$

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4.0 Electrical Specifications

Table 3: Absolute Maximum Ratings



Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These conditions represent a stress rating only, and functional operation of the device at these or any other conditions above the operational limits noted in this specification is not implied. Exposure to maximum rating conditions for extended conditions may affect device performance, functionality, and reliability.

PARAMETER	SYMBOL		MAX.	UNITS
Supply Voltage (V _{SS} = ground)	V _{DD}	V _{ss} -0.5	7	V
Input Voltage, dc	Vi	V _{ss} -0.5	V _{DD} +0.5	V
Output Voltage, dc	Vo	V _{ss} -0.5	V _{DD} +0.5	V
Input Clamp Current, dc (V _I <0 or V _I >V _{DD})	LIK /	-50	2 50	mA
Output Clamp Current, dc (V _I < 0 or V _I > V _{DD})	(I _{ok})	<50	50	mA
Storage Temperature Range (non-condensing)	Тs	-65	150	°C
Ambient Temperature Range, Under Bias	Т_ 🔿	-55	125	°C
Junction Temperature	TJ	\mathcal{S}	125	°C
Lead Temperature (soldering, 10s)	\mathbb{S}	\checkmark	260	°C
Input Static Discharge Voltage Protection (MIL-STD 883E, Method 3015.7)			2	kV



CAUTION: ELECTROSTATIC SENSITIVE DEVICE

Permanent damage resulting in a loss of functionality or performance may occur if this device is subjected to a high-energy electrostatic discharge.

Table 4: Operating Conditions

PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION	MIN.	TYP.	MAX.	UNITS
Supply Voltage	VDD	3.3V ± 10%	3.0	3.3	3.6	V
Ambient Operating Temperature Range	T₄		0		70	°C
Crystal Resonator Frequency	f _{XTAL}	Fundamental Mode	5	13.5	18	MHz
Crystal Resonator Motional Capacitance	C _{1(xtal)}	AT cut		25		fF
Crystal Loading Capacitance	$C_{L(xtal)}$	AT cut		20		pF



Table 5: DC Electrical Specifications

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Unless otherwise stated, $V_{DD} = 3.3V \pm 10\%$, no load on any output, and ambient temperature range $T_A = 0^{\circ}C$ to 70°C. Parameters denoted with an asterisk () represent nominal characterization data and are not production tested to any specific limits. Where given, MIN and MAX characterization data are $\pm 3\sigma$ from typical. Negative currents indicate current flows out of the device.

PARAMETER	SYMBOL	CONDITIONS/DESCRIPTION	MIN.	түр.	MAX.	UNITS
Overall			$\langle \langle C \rangle$	ソ		
Supply Current, Dynamic, with Loaded Outputs	I _{DD}	f _{XTAL} = 13.5MHz; C _L = 10pF, V _{DD} = 3.6V	$\langle \rangle \rangle$	30		mA
Supply Current, Static	I _{DD}	XIN = 0V, V _{DD} = 3.6V	\vee	3		mA
Voltage Controlled Crystal Oscillator						
Crystal Loading Capacitance	C _{L(xtal)}	As seen by a crystal connected to XIN and XOUT (@ $V_{XTUNE} = 1V$)	6	20		pF
Crystal Resonator Motional Capacitance	C _{1(xtal)}	AT cut	$\langle \rangle$	25		fF
VCXO Tuning Range		$f_{XTAL} = 13.5 MHz; C_{L(xtal)} = 20pF; C_{1(xtal)} = 25 fF$	\mathbb{N}	300		ppm
VCXO Tuning Characteristic		Note: positive change of XTUNE ≠ positive change of VCXO frequency		150		ppm/V
Crystal Drive Level		$R_{XTAL}=20\Omega; C_L=20pF$	\mathcal{D}	200		uW
Clock Output (CLK)						
High-Level Output Source Current *	I _{он}	V6=2.0V		-40		mA
Low-Level Output Sink Current *	loy	V ₀ = 0.4V		17		mA
Output langed an ex *	ZOH	$V_{O} = 0.1 V_{DD}$; output driving high		25		0
Output Impedance *	ZOL	$V_{O} = 0.1 V_{DD}$; output driving low		25		Ω
Short Circuit Source Current *	V _{OSH}	$V_0 = 0V$; shorted for 30s, max.		-55		mA
Short Circuit Sink Current *	HOSL	$V_0 = 3.3V$; shorted for 30s, max.		55		mA



Table 6: AC Timing Specifications

Unless otherwise stated, V_{DD} = 3.3V ± 10%, no load on any output, and ambient temperature range T_A = 0°C to 70°C. Parameters denoted with an asterisk () represent nominal characterization data and are not production tested to any specific limits. Where given, MIN and MAX characterization data are ± 3 σ from typical.

$\frac{t_{VCXOSTB}}{t_{PLLSTB}}$ $t_{j(\Delta P)}$ $t_{j(LT)}$ t_{r} t_{r}	From power validFrom VCXO stable(unless otherwise noted in Frequency Table)Ratio of high pulse width (as measured from rising edge to next falling edge at $V_{DD}/2$) to one clock periodFrom rising edge to next rising edge at $V_{DD}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ VDD = 3.3V; $V_0 = 0.8V$ to 3.0V; $C_L = 10pF$ VDD = 3.3V; $V_0 = 0.8V$ to 0.3V; $C_L = 10pF$	10 500 390 155 1.7 1.7	55	ms us ppm % ps ps ps ns ns
t_{PLLSTB} $t_{j(\Delta P)}$ $t_{j(LT)}$ t_{r}	From VCXO stable (unless otherwise noted in Frequency Table) Ratio of high pulse width (as measured from rising edge to next falling edge at $V_{DD}/2$) to one clock period From rising edge to next rising edge at $V_{DD}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ VDD = 3.3V; $V_0 = 0.8V$ to 3.0V; $C_L = 10pF$	500 390 155 1.7		us ppm % ps ps ns
t _{j(ΔP)} t _{j(LT)} t _r	(unless otherwise noted in Frequency Table)Ratio of high pulse width (as measured from rising edge to next falling edge at $V_{DD}/2$) to one clock periodFrom rising edge to next rising edge at $V_{DD}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ compared to ideal clock source $V_{DD} = 3.3V$; $V_Q = 0.8V$ to $3.0V$; $C_L = 10pF$	390 155 1.7		ppm % ps ps ns
t _{j(LT)}	Ratio of high pulse width (as measured from rising edge to next falling edge at $V_{DD}/2$) to one clock period45From rising edge to next rising edge at $V_{DD}/2$, $C_L = 10pF$ 7From 0-500 µs at $V_{DD}/2$, $C_L = 10pF$ 7V_{DD} = 3.3V; $V_Q = 0.8V$ to 3.0V; $C_L = 10pF$	390 155 1.7		% ps ps ns
t _{j(LT)}	edge to next falling edge at $V_{DD}/2$ to one clock period From rising edge to next rising edge at $V_{DB}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ compared to ideal clock source $V_{DD} = 3.3V$; $V_Q = 0.8V$ to 3.0V; $C_L = 10pF$	390 155 1.7	55	ps ps ns
t _{j(LT)}	edge to next falling edge at $V_{DD}/2$ to one clock period From rising edge to next rising edge at $V_{DB}/2$, $C_L = 10pF$ From 0-500µs at $V_{0D}/2$, $C_L = 10pF$ compared to ideal clock source $V_{DD} = 3.3V$; $V_Q = 0.8V$ to 3.0V; $C_L = 10pF$	390 155 1.7	55	ps ps ns
t _{j(LT)}	$C_{L} = 10 \text{pF}$ From 0-500 µs at V _{0D} /2, $C_{L} = 10 \text{pF}$ compared to ideal clock source $V_{DD} = 3.3 \text{V}; V_{Q} = 0.8 \text{V} \text{ to } 3.0 \text{V}; C_{L} = 10 \text{pF}$	155 1.7		ps ns
tr	compared to ideal clock source $V_{DD} = 3.3V; V_O = 0.8V$ to 3.0V; $C_L = 10pF$	1.7		ns
				-
t _f	$V_{DD} = 3.3V; V_0 = 3.0V$ to 0.3V; $C_L = 10pF$	1.7		ns
				-



5.0 Package Information

Table 7: 8-pin SOIC (0.150") Package Dimensions

		DIMEN	SIONS		
	INC	HES	MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
А	0.061	0.068	1.55	1.73	
A1	0.004	0.0098	0.102	0.249	
A2	0.055	0.061	1.40	1.55	
В	0.013	0.019	0.33	0.49	
С	0.0075	0.0098	0.191	0.249	
D	0.189	0.196	4.80	4.98	
Е	0.150	0.157	3.81	3.99	
е	0.050 BSC		1.27	BSC	
Н	0.230	0.244	5.84	6.20	
h	0.010	0.016	0.25	0.41	
L	0.016	0.035	0.41	0.89	
Θ	0°	8°	0°	8 °	

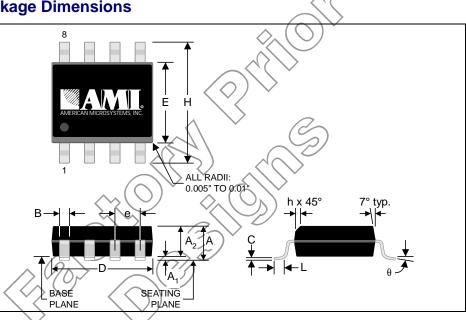


Table 8: 8-pin SOIC (0.150") Package Characteristics

PARAMETER	SYMBOL		TYP.	UNITS
Thermal Impedance, Junction to Free-Air 8-pin 0.150" SOIC	ALO	Air flow = 0 m/s	110	°C/W
Lood Inductorian Calif		Corner lead	2.0	- nH
Lead Inductance, Self	11	Center lead	1.6	
Lead Inductance, Mutual) L ₁₂	Any lead to any adjacent lead	0.4	nH
Lead Capacitance, Bulk	C ₁₁	Any lead to V _{SS}	0.27	pF



6.0 Ordering Information

Table 9: Device Ordering Codes

				\searrow
ORDERING CODE	DEVICE NUMBER	PACKAGE TYPE	OPERATING TEMPERATURE RANGE	SHIPPING CONFIGURATION
11640-101	FS6128-01	8-pin (0.150") SOIC (Small Outline Package)	0°C to 70°C (Commercial)	Tape and Reel
11640-111	FS6128-01	8-pin (0.150") SOIC (Small Outline Package)	0°C to 70°C (Commercial)	Tubes
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7.0 Revision Information

DATE	PAGE	DESCRIPTION
4/24/00	5, 7	Fixed formatting errors

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